



## Product Change Notification - JAON-30NGXA111

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**Date:**

31 Jan 2020

**Product Category:**

Interface- Controller Area Network (CAN); Interface- LIN Transceiver

**Affected CPNs:**



**Notification subject:**

CCB 4036 and 4036.001 Initial Notice: Qualification of MTAI as an additional assembly site for selected Atmel products of the 77k wafer technology available in 8L and 14L SOIC packages.

**Notification text:**

**PCN Status:**

Initial notification

**PCN Type:**

Manufacturing Change

**Microchip Parts Affected:**

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of MTAI as an additional assembly site for selected Atmel products of the 77k wafer technology available in 8L and 14L SOIC packages.

**Pre Change:**

For 14L SOIC package: Assembled at ASSH assembly site using EN-4900GC die attach and G700 mold compound material.

For 8L SOIC package: Assembled at ANAP assembly site using 8290 die attach and G700 mold compound material.

**Post Change:**

For 14L SOIC package: Assembled at ASSH assembly site using EN-4900GC die attach and G700 mold compound material or assembled at MTAI using 8390A die attach and G600V mold compound material.

For 8L SOIC package: Assembled at ANAP assembly site using 8290 die attach and G700 mold compound material or assembled at MTAI using 8390A die attach and G600V mold compound material.

**Pre and Post Change Summary:**

**For 14L SOIC Package:**

	Pre Change	Post Change	
Assembly Site	ASE-Shanghai (ASSH)	ASE-Shanghai (ASSH)	Microchip Technology Thailand (HQ) (MTAI)
Wire material	CuPdAu	CuPdAu	CuPdAu
Die attach material	EN-4900GC	EN-4900GC	8390A



<b>Molding compound material</b>	G700	G700	G600V
<b>Lead frame material</b>	CDA194	CDA194	CDA194
<b>Lead Plating</b>	NiPd-AgPd	NiPd-AgPd	Matte Tin

**For 8L SOIC Package:**

	<b>Pre Change</b>	<b>Post Change</b>	
<b>Assembly Site</b>	Amkor Technology Philippine (ANAP)	Amkor Technology Philippine (ANAP)	Microchip Technology Thailand (HQ) (MTAI)
<b>Wire material</b>	CuPdAu	CuPdAu	CuPdAu
<b>Die attach material</b>	8290	8290	8390A
<b>Molding compound material</b>	G700	G700	G600V
<b>Lead frame material</b>	CDA194	CDA194	CDA194
<b>Lead Plating</b>	NiPd-AgPd	NiPd-AgPd	Matte Tin

**Impacts to Data Sheet:**

None

**Change Impact:**

None

**Reason for Change:**

To improve on-time delivery performance by qualifying MTAI as an additional assembly site.

**Change Implementation Status:**

In Progress

**Estimated Qualification Completion Date:**

August 2020

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts. **Time Table Summary:**

	<b>January 2020</b>					->	<b>August 2020</b>				
	Workweek	01	02	03	04		05	32	33	34	35
Initial PCN Issue Date					X						
Qual Report Availability							X				
Final PCN Issue Date							X				

**Method to Identify Change:**

Traceability code

**Qualification Plan:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

**Revision History:**



**January 31, 2020:** Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):**

[PCN JAON-30NGXA111 Qual Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

**Terms and Conditions:**

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**MICROCHIP**

## **QUALIFICATION PLAN SUMMARY**

**PCN #: JAON-30NGXA111**

**Date**

**November 5, 2019**

**Qualification of MTAI as an additional assembly site for selected Atmel products of the 77k wafer technology available in 14L SOIC package. The selected Atmel products of the 77k wafer technology available in 8L SOIC package will qualify by similarity (QBS). This is an automotive AEC-Q006 qualification.**

**Purpose:** Qualification of MTAI as an additional assembly site for selected Atmel products of the 77k wafer technology available in 14L SOIC package. The selected Atmel products of the 77k wafer technology available in 8L SOIC package will qualify by similarity (QBS). This is an automotive AEC-Q006 qualification.

**CCB No.:** 4036 and 4036.001

<u>Misc.</u>	Assembly site	MTAI
	BD Number	BDM-002272
	MP Code (MPC)	77A09JD3XVA1
	Part Number (CPN)	ATA6565-GNQW0-VAO
	MSL information	1
	Assembly Shipping Media (T/R, Tube/Tray)	T&R
	Base Quantity Multiple (BQM)	4000
<u>Lead-Frame</u>	Paddle size	155 x 95 mil
	Material	CDA194
	DAP Surface Prep	Selective Ag plating
	Treatment	Rough Cu
	Process	stamp
	Lead-lock	No
	Lead Plating	Matte tin
	Strip Size	2.756 x 9.8431 inch
	Strip Density	112units / strip
<u>Bond Wire</u>	Material	CuPdAu
<u>Die Attach</u>	Part Number	8390A
	Conductive	yes
<u>MC</u>	Part Number	G600V
<u>PKG</u>	PKG Type	SOIC
	Pin/Ball Count	14
	PKG width/size	150mil

Test Name	Conditions	Reliability Stress Read Point	Pre & Post Reliability Stress Test Temperature
Standard Pb-free Solderability	<p>J-STD-002D ; Perform 8 hours of steam aging for Matte tin finish and 1 hour steam aging for NiPdAu finish prior to testing.</p> <p>Standard Pb-free: Matte tin/ NiPdAu finish, SAC solder, wetting temp 245°C for both SMD &amp; through hole packages.</p>		
Backward Solderability	<p>J-STD-002D ; Perform 8 hour steam aging for Matte tin finish and 1 hr steam aging for NiPdAu finish prior to testing.</p> <p>Backward: Matte tin/ NiPdAu finish, SnPb solder, wetting temp 215°C for SMD.</p>		
Wire Bond Pull - WBP	Mil. Std. 883-2011		
Wire Bond Shear - WBS	CDF-AEC-Q100-001		
Physical Dimensions	Measure per JESD22 B100 and B108		
External Visual	Mil. Std. 883-2009/2010		
HTSL (High Temp Storage Life)	<p>JESD22-A103</p> <p><b>+175°C</b></p> <p>2x Stress</p>	<p><u>1st Readpoint:</u> Grade 0: 1000 hrs (+175°C)</p> <p><u>2nd Readpoint:</u> Grade 0: 2000 hrs (+175°C)</p>	Grade 0: +25°C, +150°C
Preconditioning - Required for surface mount devices	<p>J-STD-020 JESD22-A113</p> <p>+150°C Bake for 24 hours, moisture loading requirements per <b>MSL level 1+</b> 3X reflow at peak reflow temperature per Jedec-STD-020E for package type.</p>		Grade 0: +25°C
HAST	<p>JESD22-A101 or A110</p> <p><b>+130°C/85% RH for 96 hrs</b></p> <p>2x Stress</p>	<p><u>1st Readpoint:</u> Grade 0: 96 hrs (+130°C/85% RH)</p> <p><u>2nd Readpoint:</u> Grade 0: 192 hrs (+130°C/85% RH)</p>	Grade 0: +25°C, +150°C
uHAST	<p>JESD22-A102, A118, or A101</p> <p><b>+130°C/85% RH for 96 hrs</b></p>	Grade 0: 96 hrs (+130°C/85% RH)	Grade 0: +25°C
Temp Cycle	<p>JESD22-A104 and Appendix 3</p> <p>-55°C to +125°C, <b>-55°C to +150°C</b></p> <p>2x Stress</p>	<p><u>1st Readpoint:</u> Grade 0: 1500 cycles (-55°C to +150°C)</p> <p><u>2nd Readpoint:</u> Grade 0: 3000 cycles (-55°C to +150°C)</p>	Grade 0: +150°C

JAON-30NGXA111 - CCB 4036 and 4036.001 Initial Notice: Qualification of MTAI as an additional assembl

Affected Catalog Part Numbers(CPN)

ATA663211-GAQW  
ATA663254-GAQW  
ATA663254-GAQW-VAO  
ATA6562-GAQW0  
ATA6566-GAQW0  
ATA6563-GAQW0  
ATA6564-GAQW0  
ATA6562-GAQW1  
ATA6561-GAQW  
ATA6560-GAQW  
ATA6564-GAQW1  
ATA6563-GAQW1  
ATA6566-GAQW1  
ATA6560-GAQW-N  
ATA6561-GAQW-N  
ATA6560-GAQW-VAO  
ATA6625-GAQW  
ATA6570-GNQW0  
ATA6570-GNQW1